## **INFORMATION NOTE**



N° 166/17

Dear Customer,

With this INFINEON Technologies Information Note we would like to inform you about the following

Capacity expansion by implementation of 300mm wafer diameter for Gen 10.2 and Gen 12.7 for TO220 package in addition to qualified site Great Team Backend Foundry (Dongguan), Ltd., China

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## **INFORMATION NOTE**



N° 166/17

Capacity expansion by implementation of 300mm wafer diameter for Gen 10.2 and Gen 12.7 for TO220 package on addition to qualified site Great Team Backend Foundry (Dongguan), Itd., China

Products affected: Please refer to 1\_cip16617a **Detailed Change Information:** Subject: Capacity expansion by implementation of 300mm wafer diameter for Gen 10.2 and Gen 12.7 for TO220 package on addition to qualified site Great Team Backend Foundry (Dongguan), Itd., China Reason: Infineon has successfully qualified our already well established BE locations GTBF, ASE-WH, and PSIL to handle incoming 300mm Si. This will improve the supply performance for our customers. Description: Old New ■ SETO220 Back End Location Great Team Backend Foundry Great Team Backend Foundry (Dongguan), Ltd., China (Dongguan, Ltd., China ASE (Weihai) Inc., China PSI, Philippines Product Identification: Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product. Impact of Change: No change in form, fit and function. Attachments: 1\_cip16617a List of affected products Intended start of 2018-01-15 delivery:

If you have any questions, please do not hesitate to contact your local Sales office.

INF N° 166/17 Capacity expansion by implementation of 300mm wafer

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Sales Name	SP number	OPN	Package
IRF1324PBF	SP001561460	IRF1324PBF	PG-TO220-3
IRF1404ZPBF	SP001574476	IRF1404ZPBF	PG-TO220-3
IRF2804PBF	SP001571174	IRF2804PBF	PG-TO220-3
IRF4104PBF	SP001554010	IRF4104PBF	PG-TO220-3
IRFB7434PBF	SP001575514	IRFB7434PBF	PG-TO220-3
IRFB7437PBF	SP001556080	IRFB7437PBF	PG-TO220-3
IRFB7440GPBF	SP001577780	IRFB7440GPBF	PG-TO220-3
IRFB7440PBF	SP001566700	IRFB7440PBF	PG-TO220-3
IRFB7446PBF	SP001577760	IRFB7446PBF	PG-TO220-3